IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	© Copyright 2005. IPC	Material Composition Declaration Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both nternational and Pan-American copyright conventions.			der both le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi				ials and Mfg Information				
upplier Inform	ation													
Company name*			Company unique ID			Ţ	Unique ID Authority				Response Date*			
nsemi										2022-02-11				
Contact Name			Title - Contact			F	Phone - Contact*				Email - Contact*			
Product-Env-Stewar	rds	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
uthorized Represer	ntative*	Title - Representative			F	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
Requester	r Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	M	Ianufacturing Site	V	Veight*	UOM	Unit Type
	RS1KFP			800V Fast Rect SOD123HE			2022-02-11		T	TSCBE		1.80026	mg	Each
	Proccess Informatio								,				·	
2 2			Cerminal Base Alloy J-STD-020 MSL		Rating						er of Reflow Cyc	eles		
Matte Tin	n (Sn) - annealed	C	U Alloy	1			260	(C	30	second	ls 3		
omments														
vel 1 - maximum ti	ime at peak temperature	during sol	dering is 10-3	0 seconds										
or more informatio	on regarding material co	mposition j	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's St											
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature R		,									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	1.3299	mg	Supplier	Iron (Fe)	7439-89-6		0.0013	mg
			Supplier	Copper (Cu)	7440-50-8		1.3282	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0004	mg
Die	2.0218	mg	Supplier	Silicon (Si)	7440-21-3		1.8196	mg
			В	Nickel (Ni)	7440-02-0		0.0131	mg
			Supplier	Gold (Au)	7440-57-5		0.003	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.186	mg
Die Attach Solder	0.41096	mg	Supplier	Silver (Ag)	7440-22-4		0.0103	mg
			A	Lead (Pb)	7439-92-1	7a	0.3801	mg
			Supplier	Tin (Sn)	7440-31-5		0.0205	mg
Lead Frame	12.3086	mg	Supplier	Iron (Fe)	7439-89-6		0.0123	mg
			Supplier	Copper (Cu)	7440-50-8		12.2926	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0037	mg
Mold Compound-Black	5.7288	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.5757	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0286	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		4.8953	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.2292	mg
Plating	2.0E-4	mg	Supplier	Tin (Sn)	7440-31-5		0.0002	mg